

Wafer Holder and Method of Producing a Semiconductor Wafer

Abstract:

The invention relates to a wafer holder (chuck) having a support for fixing a semiconductor wafer during grinding and to a method of producing a semiconductor wafer which has two flat-ground sides and a radiused edge. The wafer holder has a support which is composed of a soft material. The method is one wherein the semiconductor wafer is fixed on a wafer holder having a soft support during grinding of the first side and is fixed on a wafer holder having a hard support during grinding of the second side.

(Figure 2b)